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INT-03-008

May 21, 2004

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/807,036 03/23/04 |
Thomas Aisenbrey
LOW COST THERMAL MANAGEMENT DEVICE
OR HEAT SINK USING CONDUCTIVE
PLASTICS OR CONDUCTIVE COMPOSITES
| _____ |

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on May 24, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date Stephen B. Ackerman 5/24/04

INT-03-008

U.S. Patent Application Publication US 2002/0109634 A1 to Aisenbrey, "Low Cost Antennas Using Conductive Plastics or Conductive Composites," discusses low cost antennas formed of conductive loaded resin-based materials.

U.S. Patent Application INT-01-002_CIP, filed 12/04/02, Serial No. 10/309,429, assigned to the same assignee, "Low Cost Antennas Using Conductive Plastics or Conductive Composites," discusses antennas formed of conductive loaded resin-based materials comprising micron conductive powders or micron conductive fibers.

U.S. Patent 6,565,772 to Schneck, "Conductive Resin Composition," teaches a conductive resin comprising resin, a cure accelerant, and a conductive particulate.

U.S. Patent 6,451,418 to Tobita, "Heat Conductive Resin Substrate and Semiconductor Package," describes a substrate or a chip package constructed from a heat conductive resin material.

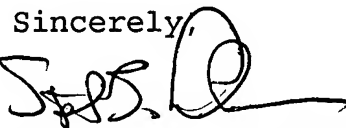
U.S. Patent 6,284,817 to Cross et al., "Conductive, Resin-Based Compositions," discloses a conductive resin-based material including aluminum oxide and zinc oxide particles.

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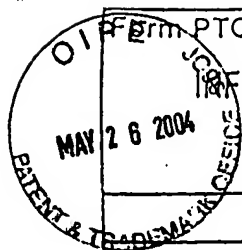
U.S. Patent 6,597,063 to Shimizu et al., "Package for Semiconductor Power Device and Method for Assembling the Same," discloses a package for a semiconductor power device.

U.S. Patent Application Publication US 2003/0183379 A1 to Krassowski et al., "Optimized Heat Sink Using High Thermal Conducting Base and Low Thermal Conducting FINs," teaches a composite heat sink comprising a graphite base and conductive plastic fins.

UK Patent Application GB 2 377 449 A to Michael Patrick Sayers, "Electrically Conductive Polymer Composition," discusses electrically conductive compositions, and to their use to prevent electrostatic discharges and to earth electrical devices.

Sincerely,


Stephen B. Ackerman,
Reg. No. 37761



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Form PTO-1449

INFORMATION DISCLOSURE CITATION
IN AN APPLICATION

(Use several sheets if necessary)

Docket Number (Optional)

INT-03-008

Application Number

10/807,036

Applicant

Thomas Aisenbrey

Filing Date

03/23/04

Group Art Unit

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILED DATE IF APPROPRIATE
	6565772	5/20/03	Schneck	252	511	9/25/01
	6451418	9/17/02	Tobita	428	297.4	3/22/00
	6284817	9/4/01	Cross et al.	523	220	2/29/00
	6597063	7/22/03	Shimizu et al.	257	687	4/4/00

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO
	GB 2377449A	1/15/03	UK Patent App.	08K	3/08 7/06		

OTHER DOCUMENTS (Including Author, Title, Date, Portmox Pages, Etc.)

-	US Patent App. INT-01-002-CIP, Ser# 10/309,429, filed 12/4/02, assigned to the same assignee, "Low Cost Antennas Using Conductive Plastics or Conductive Composites".
-	US Patent App. Pub. US 2002/0109634 A1, to Aisenbrey, Pub. Date - 8/15/02, Filed 2/14/02, US Cl. 343/700 ms.
-	US Patent App Pub. US 2003/0183379 A1, to Krassowski et al., Pub Date 10/2/03, Filed 3/29/02, US Cl. 165/185.

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.